

Docket No.: INTEL-0069



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

**EXPEDITED PROCEDURE
UNDER 37 C.F.R. §1.116**

Edward R. HURLEY et al.

Serial No.: **10/806,118**

Group Art Unit: **1725**

Confirmation No.: **2131**

Examiner: **R. Beveridge**

Filed: **March 23, 2004**

Customer No.: **34610**

For: **METALLIC SOLDER THERMAL INTERFACE MATERIAL LAYER AND
APPLICATION OF THE SAME**

**AMENDMENT AFTER FINAL REJECTION
UNDER 37 C.F.R. §1.116**

U.S. Patent and Trademark Office
Customer Window, Mail Stop AF
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In reply to the Office Action dated May 8, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims

Remarks begin after the listing of the claims.